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### What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

### Applications of "[Embedded - Microcontrollers](#)"

#### Details

Product Status	Active
Core Processor	AVR
Core Size	8/16-Bit
Speed	32MHz
Connectivity	I <sup>2</sup> C, IrDA, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	26
Program Memory Size	32KB (16K x 16)
Program Memory Type	FLASH
EEPROM Size	1K x 8
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	1.6V ~ 3.6V
Data Converters	A/D 16x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	32-UFQFN Exposed Pad
Supplier Device Package	32-UQFN (4x4)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/microchip-technology/atxmega32e5-m4n">https://www.e-xfl.com/product-detail/microchip-technology/atxmega32e5-m4n</a>

Ordering Code	Package <sup>(1)(2)(3)</sup>	Flash [Bytes]	EEPROM [Bytes]	SRAM [Bytes]	Speed [MHz]	Power supply [V]	Temp. [°C]
ATxmega32E5-AN	32A (7x7mm TQFP)	32K + 4K	1K	4K	32	1.6 – 3.6	-40 – 105
ATxmega32E5ANR <sup>(4)</sup>							
ATxmega32E5-MN	32Z (5x5mm VQFN)						
ATxmega32E5-MNR <sup>(4)</sup>							
ATxmega32E5-M4UN	32MA (4x4mm UQFN)						
ATxmega32E5-M4UNR <sup>(4)</sup>							

Notes:

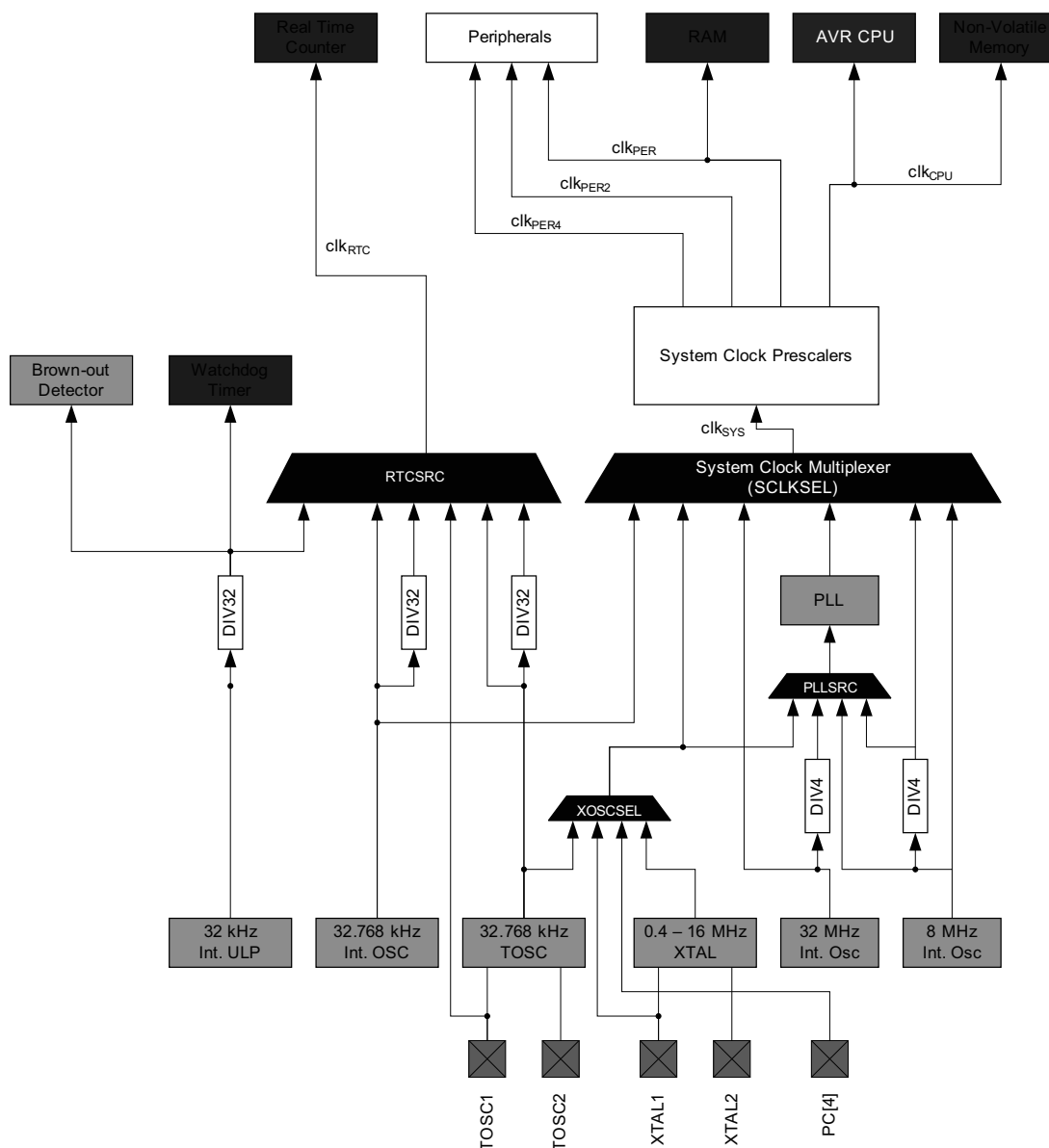
1. This device can also be supplied in wafer form. Please contact your local Atmel sales office for detailed ordering information.
2. Pb-free packaging, complies to the European Directive for Restriction of Hazardous Substances (RoHS directive). Also Halide free and fully Green.
3. For packaging information, see "Packaging Information" on page 68.
4. Tape and Reel.

Package Type	
<b>32A</b>	32-lead, 7x7mm body size, 1.0mm body thickness, 0.8mm lead pitch, thin profile plastic quad flat package (TQFP)
<b>32Z</b>	32-lead, 0.5mm pitch, 5x5mm Very Thin quad Flat No Lead Package (VQFN) Sawn
<b>32MA</b>	32-lead, 0.4mm pitch, 4x4x0.60mm Ultra Thin Quad No Lead (UQFN) Package

## 2. Typical Applications

Board controller	Sensor control	Motor control
User interface	Industrial control	Ballast control, Inverters
Communication bridges	Battery charger	Utility metering
Appliances		

**Figure 11-1. The Clock System, Clock Sources, and Clock Distribution**



## 11.3 Clock Sources

The clock sources are divided in two main groups: internal oscillators and external clock sources. Most of the clock sources can be directly enabled and disabled from software, while others are automatically enabled or disabled, depending on peripheral settings. After reset, the device starts up running from the 2MHz output of the 8MHz internal oscillator. The other clock sources, DFLL and PLL, are turned off by default.

The internal oscillators do not require any external components to run. For details on characteristics and accuracy of the internal oscillators, refer to the device datasheet.

### 11.3.1 32kHz Ultra Low Power Internal Oscillator

This oscillator provides an approximate 32kHz clock. The 32kHz ultra low power (ULP) internal oscillator is a very low power clock source, and it is not designed for high accuracy. The oscillator employs a built-in prescaler that provides a 1kHz output. The oscillator is automatically enabled/disabled when it is used as clock source for any part of the device. This oscillator can be selected as the clock source for the RTC.

### 13.4.2 Brownout Detection

The on-chip brownout detection (BOD) circuit monitors the  $V_{CC}$  level during operation by comparing it to a fixed, programmable level that is selected by the BODLEVEL fuses. If disabled, BOD is forced on at the lowest level during chip erase and when the PDI is enabled.

### 13.4.3 External Reset

The external reset circuit is connected to the external RESET pin. The external reset will trigger when the RESET pin is driven below the RESET pin threshold voltage,  $V_{RST}$ , for longer than the minimum pulse period,  $t_{EXT}$ . The reset will be held as long as the pin is kept low. The RESET pin includes an internal pull-up resistor.

### 13.4.4 Watchdog Reset

The watchdog timer (WDT) is a system function for monitoring correct program operation. If the WDT is not reset from the software within a programmable timeout period, a watchdog reset will be given. The watchdog reset is active for one to two clock cycles of the 2MHz internal oscillator. For more details, see “WDT – Watchdog Timer” on page 27.

### 13.4.5 Software Reset

The software reset makes it possible to issue a system reset from software by writing to the software reset bit in the reset control register. The reset will be issued within two CPU clock cycles after writing the bit. It is not possible to execute any instruction from when a software reset is requested until it is issued.

### 13.4.6 Program and Debug Interface Reset

The program and debug interface reset contains a separate reset source that is used to reset the device during external programming and debugging. This reset source is accessible only from external debuggers and programmers.

## 15. Interrupts and Programmable Multilevel Interrupt Controller

### 15.1 Features

- Short and predictable interrupt response time
- Separate interrupt configuration and vector address for each interrupt
- Programmable multilevel interrupt controller
  - Interrupt prioritizing according to level and vector address
  - Three selectable interrupt levels for all interrupts: low, medium, and high
  - Selectable, round-robin priority scheme within low-level interrupts
  - Non-maskable interrupts for critical functions
- Interrupt vectors optionally placed in the application section or the boot loader section

### 15.2 Overview

Interrupts signal a change of state in peripherals, and this can be used to alter program execution. Peripherals can have one or more interrupts, and all are individually enabled and configured. When an interrupt is enabled and configured, it will generate an interrupt request when the interrupt condition is present. The programmable multilevel interrupt controller (PMIC) controls the handling and prioritizing of interrupt requests. When an interrupt request is acknowledged by the PMIC, the program counter is set to point to the interrupt vector, and the interrupt handler can be executed.

All peripherals can select between three different priority levels for their interrupts: low, medium, and high. Interrupts are prioritized according to their level and their interrupt vector address. Medium-level interrupts will interrupt low-level interrupt handlers. High-level interrupts will interrupt both medium- and low-level interrupt handlers. Within each level, the interrupt priority is decided from the interrupt vector address, where the lowest interrupt vector address has the highest interrupt priority. Low-level interrupts have an optional round-robin scheduling scheme to ensure that all interrupts are serviced within a certain amount of time.

Non-maskable interrupts (NMI) are also supported, and can be used for system critical functions.

### 15.3 Interrupt Vectors

The interrupt vector is the sum of the peripheral's base interrupt address and the offset address for specific interrupts in each peripheral. The base addresses for the Atmel AVR XMEGA E5 devices are shown in Table 15-1. Offset addresses for each interrupt available in the peripheral are described for each peripheral in the XMEGA AU manual. For peripherals or modules that have only one interrupt, the interrupt vector is shown in Table 15-1. The program address is the word address.

**Table 15-1. Peripheral Module Address Map**

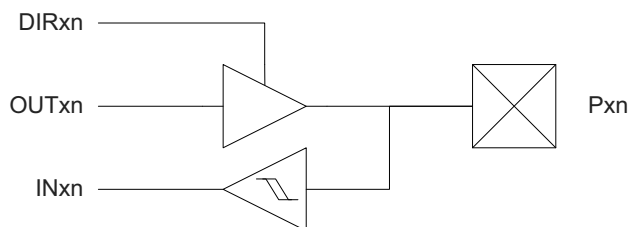
Program address (base address)	Source	Interrupt description
0x0000	RESET	
0x0002	OSCF_INT_vect	Crystal oscillator failure and PLL lock failure interrupt vector (NMI)
0x0004	PORTR_INT_vect	Port R Interrupt vector
0x0006	EDMA_INT_base	EDMA Controller Interrupt base
0x000E	RTC_INT_base	Real time counter interrupt base
0x0012	PORTC_INT_vect	Port C interrupt vector
0x0014	TWIC_INT_base	Two-wire interface on Port C interrupt base
0x0018	TCC4_INT_base	Timer/counter 4 on port C interrupt base

## 16.3 Output Driver

All port pins (Pxn) have programmable output configuration. The port pins also have configurable slew rate limitation to reduce electromagnetic emission.

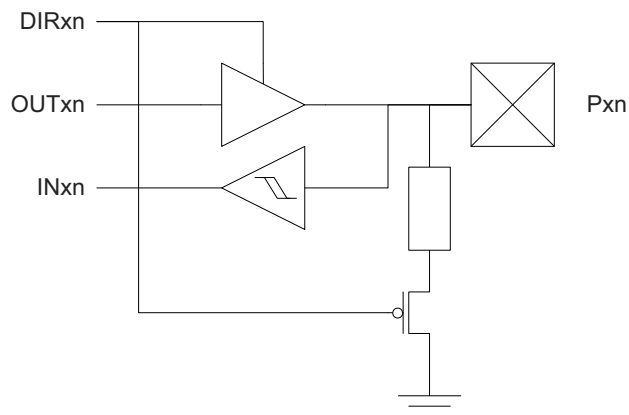
### 16.3.1 Push-pull

Figure 16-1. I/O Configuration - Totem-pole



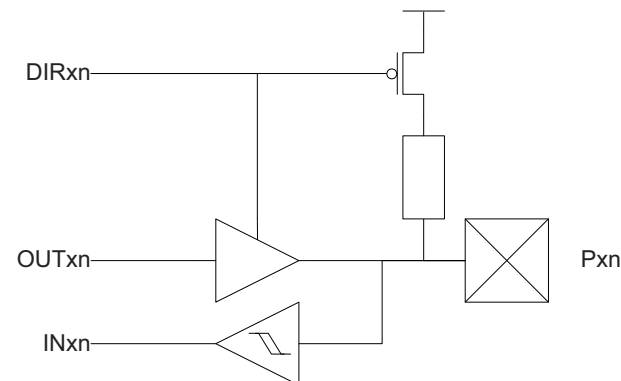
### 16.3.2 Pull-down

Figure 16-2. I/O Configuration - Totem-pole with Pull-down (on input)



### 16.3.3 Pull-up

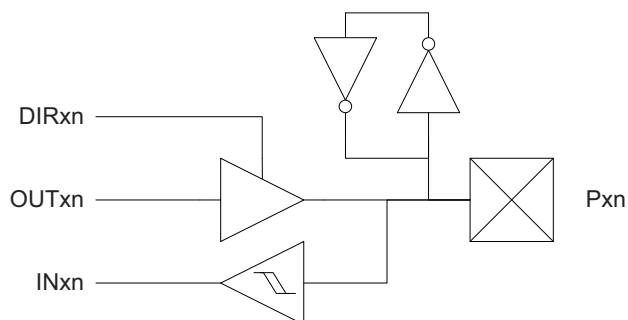
Figure 16-3. I/O Configuration - Totem-pole with Pull-up (on input)



### 16.3.4 Bus-keeper

The bus-keeper's weak output produces the same logical level as the last output level. It acts as a pull-up if the last level was '1', and pull-down if the last level was '0'.

Figure 16-4. I/O Configuration - Totem-pole with Bus-keeper



### 16.3.5 Others

Figure 16-5. Output Configuration - Wired-OR with Optional Pull-down

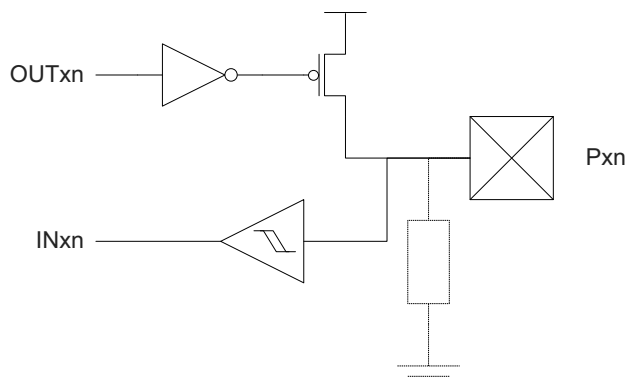
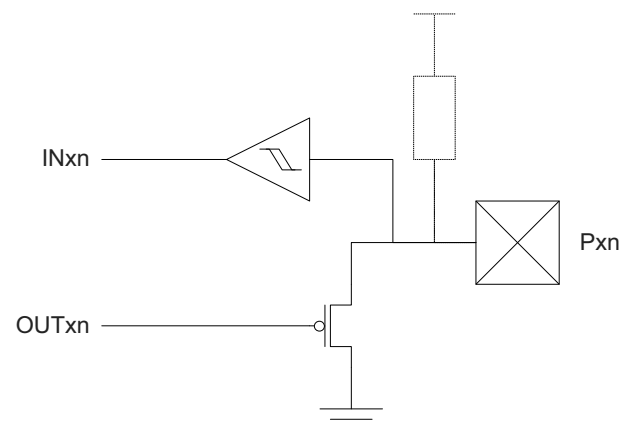


Figure 16-6. I/O Configuration - Wired-AND with Optional Pull-up



The output override disable unit can disable the waveform output on selectable port pins to optimize the pins usage. This is to free the pins for other functional use, when the application does not need the waveform output spread across all the port pins as they can be selected by the OTMX configurations.

The waveform extension is available for TCC4 and TCC5. The notation of this is WEXC.



## 22. TWI – Two-Wire Interface

### 22.1 Features

- One two-wire interface
  - Phillips I<sup>2</sup>C compatible
  - System Management Bus (SMBus) compatible
- Bus master and slave operation supported
  - Slave operation
  - Single bus master operation
  - Bus master in multi-master bus environment
  - Multi-master arbitration
  - Bridge mode with independent and simultaneous master and slave operation
- Flexible slave address match functions
  - 7-bit and general call address recognition in hardware
  - 10-bit addressing supported
  - Address mask register for dual address match or address range masking
  - Optional software address recognition for unlimited number of addresses
- Slave can operate in all sleep modes, including power-down
- Slave address match can wake device from all sleep modes
- 100kHz, 400kHz, and 1MHz bus frequency support
- Slew-rate limited output drivers
- Input filter for bus noise and spike suppression
- Support arbitration between start/repeated start and data bit (SMBus)
- Slave arbitration allows support for address resolve protocol (ARP) (SMBus)
- Supports SMBUS Layer 1 timeouts
- Configurable timeout values
- Independent timeout counters in master and slave (Bridge mode support)

### 22.2 Overview

The two-wire interface (TWI) is a bidirectional, two-wire communication interface. It is I<sup>2</sup>C and System Management Bus (SMBus) compatible. The only external hardware needed to implement the bus is one pull-up resistor on each bus line.

A device connected to the bus must act as a master or a slave. One bus can have many slaves and one or several masters that can take control of the bus.

The TWI module supports master and slave functionality. The master and slave functionality are separated from each other, and can be enabled and operate simultaneously and separately. The master module supports multi-master bus operation and arbitration. It contains the baud rate generator. Quick command and smart mode can be enabled to auto-trigger operations and reduce software complexity. The master can support 100kHz, 400kHz, and 1MHz bus frequency.

The slave module implements 7-bit address match and general address call recognition in hardware. 10-bit addressing is also supported. A dedicated address mask register can act as a second address match register or as a register for address range masking. The slave continues to operate in all sleep modes, including power-down mode. This enables the slave to wake up the device from all sleep modes on TWI address match. It is possible to disable the address matching to let this be handled in software instead. By using the bridge option, the slave can be mapped to different pin locations. The master and slave can support 100kHz, 400kHz, and 1MHz bus frequency.

The TWI module will detect START and STOP conditions, bus collisions, and bus errors. Arbitration lost, errors, collision, and clock hold on the bus are also detected and indicated in separate status flags available in both master and slave modes.

XCKn	Transfer Clock for USART n
RXDn	Receiver Data for USART n
TXDn	Transmitter Data for USART n
SS	Slave Select for SPI
MOSI	Master Out Slave In for SPI
MISO	Master In Slave Out for SPI
SCK	Serial Clock for SPI

### 32.1.6 Oscillators, Clock, and Event

TOSCn	Timer Oscillator pin n
XTALn	Input/Output for Oscillator pin n
CLKOUT	Peripheral Clock Output
EVOUT	Event Channel Output
RTCCOUT	RTC Clock Source Output

### 32.1.7 Debug/System Functions

RESET	Reset pin
PDI_CLK	Program and Debug Interface Clock pin
PDI_DATA	Program and Debug Interface Data pin

## 32.2 Alternate Pin Functions

The tables below show the primary/default function for each pin on a port in the first column, the pin number in the second column, and then all alternate pin functions in the remaining columns. The head row shows what peripheral that enable and use the alternate pin functions.

For better flexibility, some alternate functions also have selectable pin locations for their functions, this is noted under the first table where this apply.

**Table 32-1. PORT A – Alternate Functions**

PORT A	Pin#	ADCA POS/ GAINPOS	ADCA NEG/ GAINNEG	DACA	ACA POS	ACA NEG	ACA OUT	REFA
PA0	6	ADC 0	ADC 0		AC0	AC0		AREF
PA1	5	ADC 1	ADC 1		AC1	AC1		
PA2	4	ADC 2	ADC 2	DAC0	AC2			
PA3	3	ADC 3	ADC 3	DAC1	AC3	AC3		
PA4	2	ADC 4	ADC 4		AC4			
PA5	31	ADC 5	ADC 5		AC5	AC5		
PA6	30	ADC 6	ADC 6		AC6		AC1OUT	
PA7	29	ADC 7	ADC 7			AC7	AC0OUT	

**Table 32-2. PORT C – Alternate Functions**

PORT C	Pin #	TCC4	WEXC	TCC5	USARTC0	SPIC	TWI	XCL (LUT)	EXTCLK	AC OUT
PC0	16	OC4A	OC4ALS				SDA	IN1/OUT0		
PC1	15	OC4B	OC4AHS		XCK0		SCL	IN2		
PC2	14	OC4C	OC4BLS		RXD0			IN0		
PC3	13	OC4D	OC4BHS		TXD0			IN3		
PC4	12	OC4A	OC4CLS	OC5A		$\overline{SS}$		IN1/OUT0	EXTCLK	
PC5	11	OC4B	OC4CHS	OC5B	XCK0	SCK		IN2		
PC6	10	OC4C	OC4DLS		RXD0	MISO		IN0		AC1OUT
PC7	9	OC4D	OC4DHS		TXD0	MOSI		IN3		AC0OUT

**Table 32-3. Debug – Program and Debug Functions**

DEBUG	Pin #	PROG
RESET	8	PDI CLOCK
PDI	7	PDI DATA

### 33. Peripheral Module Address Map

The address maps show the base address for each peripheral and module in XMEGA E5. For complete register description and summary for each peripheral module, refer to the XMEGA E Manual.

**Table 33-1. Peripheral Module Address Map**

Base Address	Name	Description
0x0000	GPIO	General Purpose IO Registers
0x0010	VPORT0	Virtual Port A
0x0014	VPORT1	Virtual Port C
0x0018	VPORT2	Virtual Port D
0x001C	VPORT3	Virtual Port R
0x0030	CPU	CPU
0x0040	CLK	Clock Control
0x0048	SLEEP	Sleep Controller
0x0050	OSC	Oscillator Control
0x0060	DFLLRC32M	DFLL for the 32MHz Internal Oscillator
0x0070	PR	Power Reduction
0x0078	RST	Reset Controller
0x0080	WDT	Watch-Dog Timer
0x0090	MCU	MCU Control
0x00A0	PMIC	Programmable Multilevel Interrupt Controller
0x00B0	PORTCFG	Port Configuration
0x00D0	CRC	CRC Module
0x0100	EDMA	Enhanced DMA Controller
0x0180	EVSYS	Event System
0x01C0	NVM	Non Volatile Memory (NVM) Controller
0x0200	ADCA	Analog to Digital Converter on port A
0x0300	DACA	Digital to Analog Converter on port A
0x0380	ACA	Analog Comparator pair on port A
0x0400	RTC	Real Time Counter
0x0460	XCL	XMEGA Custom Logic Module
0x0480	TWIC	Two-Wire Interface on port C
0x0600	PORTA	Port A
0x0640	PORTC	Port C
0x0660	PORTD	Port D

Symbol	Parameter	Condition <sup>(2)</sup>		Min.	Typ.	Max.	Units
DNL <sup>(1)</sup>	Differential non-linearity	Differential mode	16ksps, V <sub>REF</sub> = 3V		1		lsb
			16ksps, V <sub>REF</sub> = 1V		2		
			300ksps, V <sub>REF</sub> = 3V		1		
			300ksps, V <sub>REF</sub> = 1V		2		
		Single ended unsigned mode	16ksps, V <sub>REF</sub> = 3.0V		1	1.5	
			16ksps, V <sub>REF</sub> = 1.0V		2	3	
	Offset Error	Differential mode			8		mV
			Temperature drift		0.01		mV/K
			Operating voltage drift		0.25		mV/V
	Gain Error	Differential mode	External reference		-5		mV
			AV <sub>CC</sub> /1.6		-5		
			AV <sub>CC</sub> /2.0		-6		
			Bandgap		±10		
			Temperature drift		0.02		mV/K
			Operating voltage drift		2		mV/V
	Gain Error	Single ended unsigned mode	External reference		-8		mV
			AV <sub>CC</sub> /1.6		-8		
			AV <sub>CC</sub> /2.0		-8		
			Bandgap		±10		
			Temperature drift		0.03		mV/K
			Operating voltage drift		2		mV/V

Notes: 1. Maximum numbers are based on characterisation and not tested in production, and valid for 10% to 90% input voltage range.  
2. Unless otherwise noted all linearity, offset and gain error numbers are valid under the condition that external V<sub>REF</sub> is used.

**Table 36-10. Gain Stage Characteristics**

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
R <sub>in</sub>	Input resistance	Switched		4.0		kΩ
C <sub>sample</sub>	Input capacitance	Switched		4.4		pF
	Signal range	Gain stage output	0		AV <sub>CC</sub> - 0.6	V
	Propagation delay	ADC conversion rate	1/2	1	3	Clk <sub>ADC</sub> cycles
	Clock rate	Same as ADC	100		1800	kHz

Table 36-13. Accuracy Characteristics

Symbol	Parameter	Condition		Min.	Typ.	Max.	Units
RES	Input Resolution					12	Bits
INL <sup>(1)</sup>	Integral non-linearity	$V_{REF} = \text{Ext } 1.0V$	$V_{CC} = 1.6V$		$\pm 2.0$	$\pm 3$	lsb
			$V_{CC} = 3.6V$		$\pm 1.5$	$\pm 2.5$	
		$V_{REF} = AV_{CC}$	$V_{CC} = 1.6V$		$\pm 2.0$	$\pm 4$	
			$V_{CC} = 3.6V$		$\pm 1.5$	$\pm 4$	
		$V_{REF} = \text{INT}1V$	$V_{CC} = 1.6V$		$\pm 5.0$		
			$V_{CC} = 3.6V$		$\pm 5.0$		
DNL <sup>(1)</sup>	Differential non-linearity	$V_{REF} = \text{Ext } 1.0V$	$V_{CC} = 1.6V$		$\pm 1.5$	3	
			$V_{CC} = 3.6V$		$\pm 0.6$	1.5	
		$V_{REF} = AV_{CC}$	$V_{CC} = 1.6V$		$\pm 1.0$	3.5	
			$V_{CC} = 3.6V$		$\pm 0.6$	1.5	
		$V_{REF} = \text{INT}1V$	$V_{CC} = 1.6V$		$\pm 4.5$		
			$V_{CC} = 3.6V$		$\pm 4.5$		
	Gain error	After calibration			<4		
	Gain calibration step size				4		
	Gain calibration drift	$V_{REF} = \text{Ext } 1.0V$			<0.2		mV/K
	Offset error	After calibration			<1		lsb
	Offset calibration step size				1		

Note: 1. Maximum numbers are based on characterisation and not tested in production, and valid for 5% to 95% output voltage range.

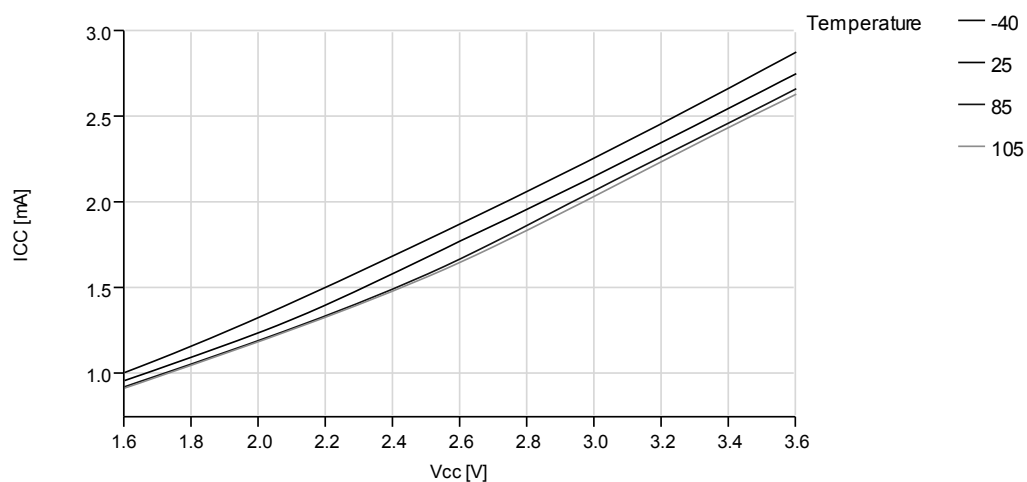
## 36.8 Analog Comparator Characteristics

Table 36-14. Analog Comparator Characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
$V_{off}$	Input offset voltage			10		mV
$I_{lk}$	Input leakage current			<10	50	nA
	Input voltage range		-0.1		$AV_{CC}$	V
	AC startup time			50		$\mu s$
$V_{hys1}$	Hysteresis, none	$V_{CC} = 1.6V - 3.6V$		0		mV
$V_{hys2}$	Hysteresis, small	$V_{CC} = 1.6V - 3.6V$		12		
$V_{hys3}$	Hysteresis, large	$V_{CC} = 1.6V - 3.6V$		28		
$t_{delay}$	Propagation delay	$V_{CC} = 3.0V, T = 85^{\circ}C$		22	30	ns
		$V_{CC} = 1.6V - 3.6V$		21	40	

**Figure 37-7. Active mode Supply Current vs.  $V_{CC}$**

$f_{SYS} = 32\text{MHz}$  internal oscillator prescaled to 8MHz



**Figure 37-8. Active Mode Supply Current vs.  $V_{CC}$**

$f_{SYS} = 32\text{MHz}$  internal oscillator

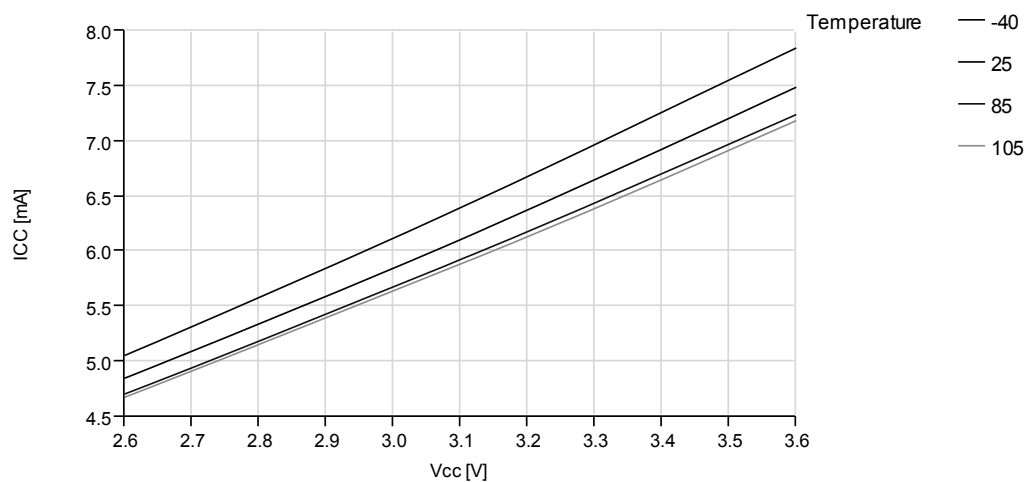
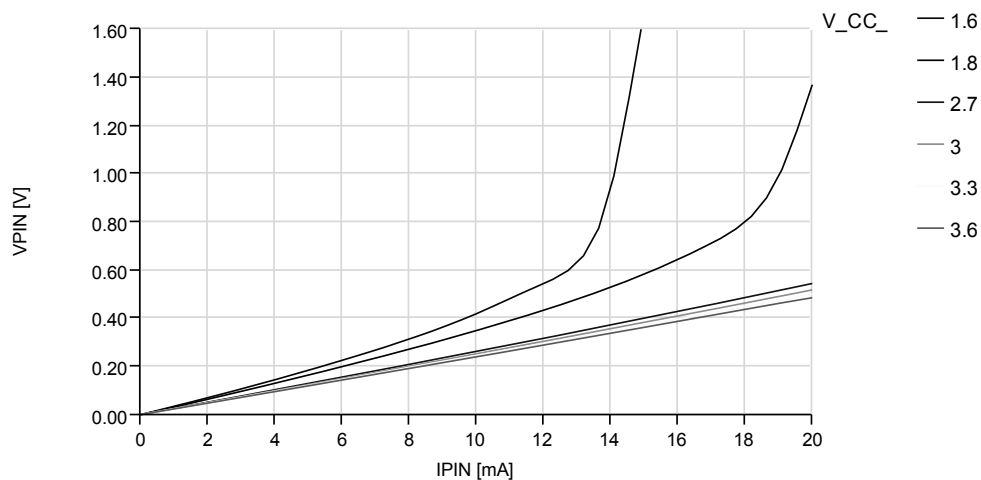


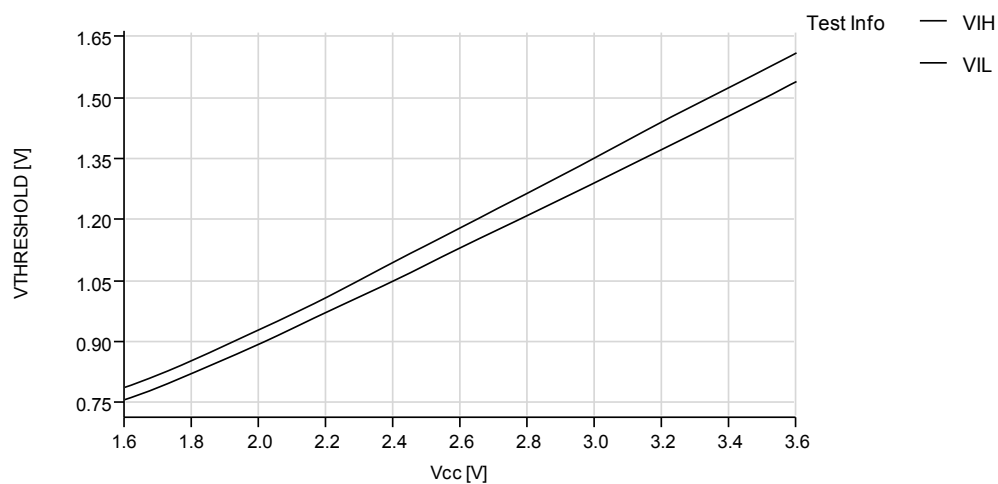
Figure 37-33. I/O Pin Output Voltage vs. Sink Current



### 37.2.3 Thresholds and Hysteresis

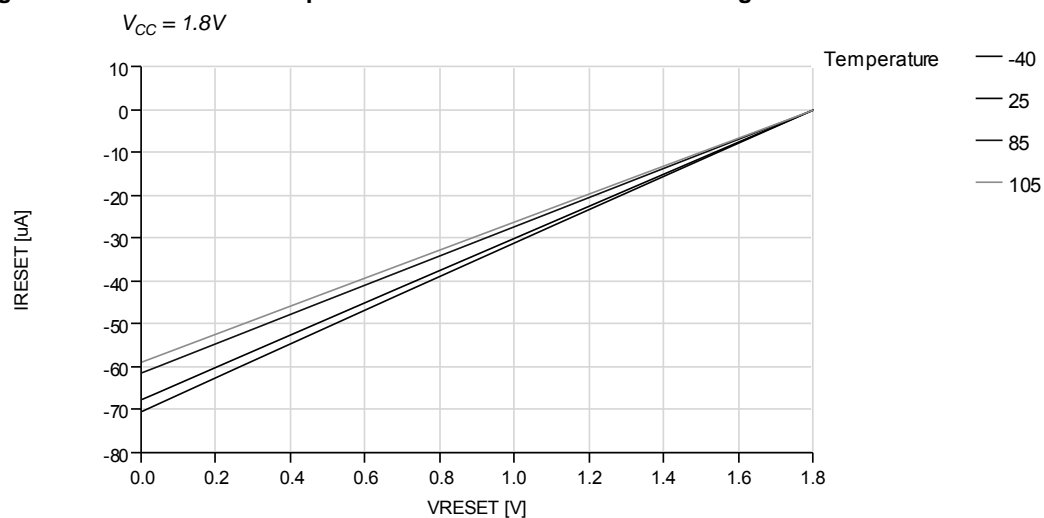
Figure 37-34. I/O Pin Input Threshold Voltage vs.  $V_{CC}$

$T = 25^{\circ}\text{C}$

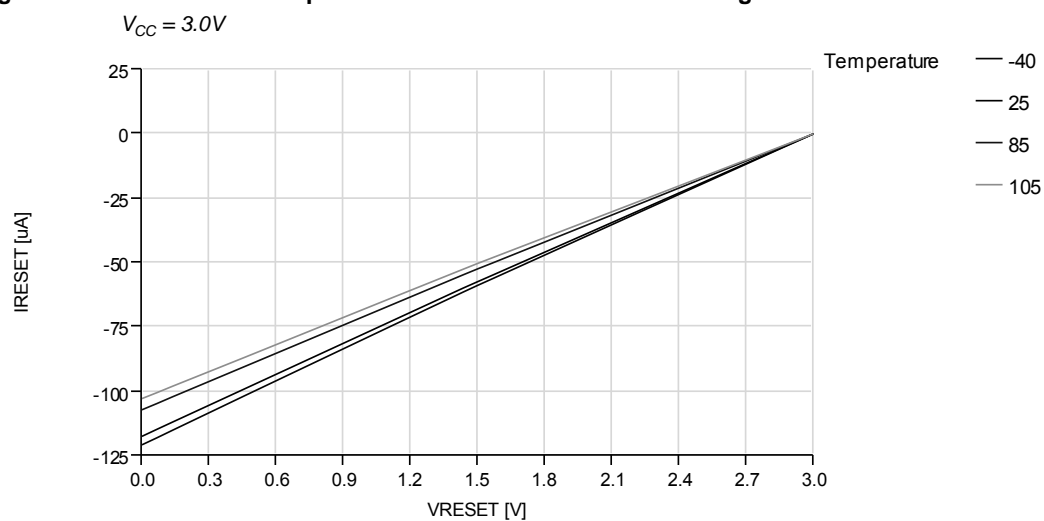




**Figure 37-63. Reset Pin Pull-up Resistor Current vs. Reset Pin Voltage**

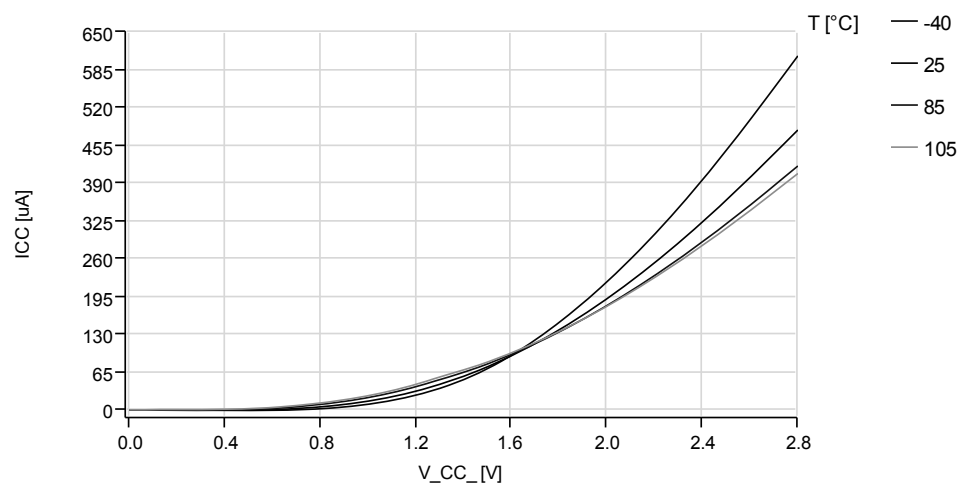


**Figure 37-64. Reset Pin Pull-up Resistor Current vs. Reset Pin Voltage**



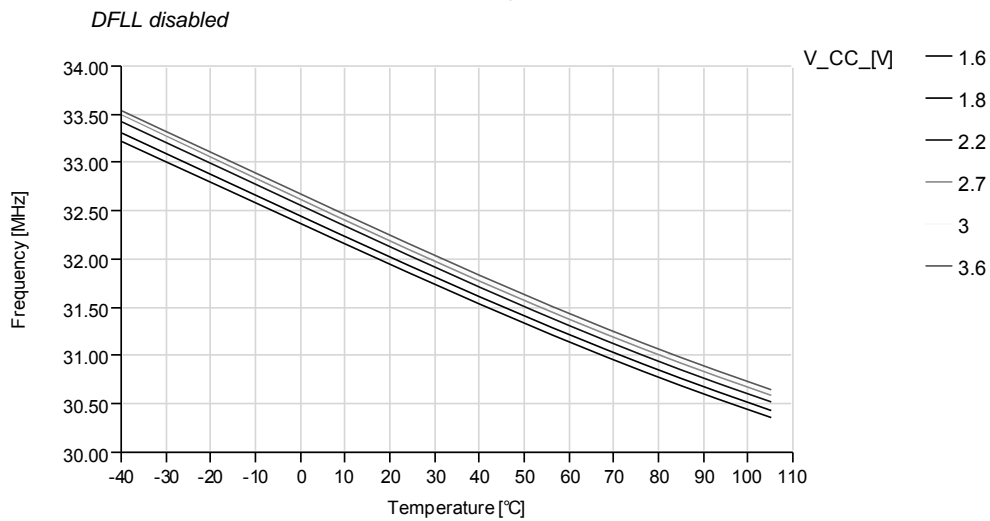
**Figure 37-69. Power-on Reset Current Consumption vs.  $V_{CC}$**

*BOD level = 3.0V, enabled in sampled mode*

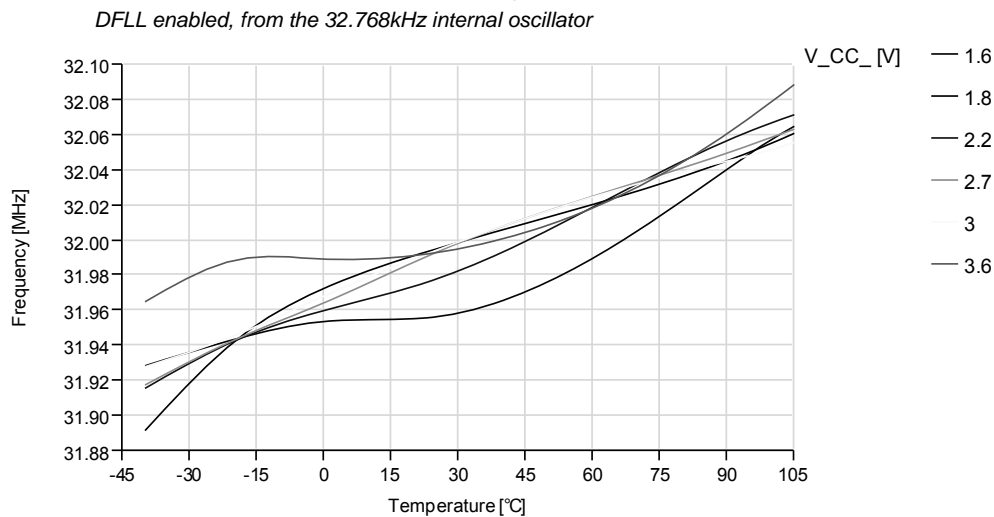


### 37.10.4 32MHz Internal Oscillator

**Figure 37-78. 32MHz Internal Oscillator Frequency vs. Temperature**



**Figure 37-79. 32MHz Internal Oscillator Frequency vs. Temperature**



## 38.2 Rev. A

- DAC: AREF on PD0 is not available for the DAC
- EDMA: Channel transfer never stops when double buffering is enabled on sub-sequent channels
- ADC: Offset correction fails in unsigned mode
- ADC: Averaging is failing when channel scan is enabled
- ADC: Averaging in single conversion requires multiple conversion triggers
- ADC accumulator sign extends the result in unsigned mode averaging
- ADC: Free running average mode issue
- ADC: Event triggered conversion in averaging mode
- AC: Flag can not be cleared if the module is not enabled
- USART: Receiver not functional when variable data length and start frame detector are enabled
- T/C: Counter does not start when CLKSEL is written
- EEPROM write and Flash write operations fails under 2.0V
- TWI master or slave remembering data
- Temperature Sensor not calibrated

**Issue: DAC: AREF on PD0 is not available for the DAC**

The AREF external reference input on pin PD0 is not available for the DAC.

**Workaround:**

No workaround. Only AREF on pin PA0 can be used as external reference input for the DAC.

**Issue: EDMA: Channel transfer never stops when double buffering is enabled on sub-sequent channels**

When the double buffering is enabled on two channels, the channels which are not set in double buffering mode are never disabled at the end of the transfer. A new transfer can start if the channel is not disabled by software.

**Workaround:**

- CHMODE = 00  
Enable double buffering on all channels or do not use channels which are not set the double buffering mode.
- CHMODE = 01 or 10  
Do not use the channel which is not supporting the double buffering mode.

**Issue: ADC: Offset correction fails in unsigned mode**

In single ended, unsigned mode, a problem appears in low saturation (zero) when the offset correction is activated. The offset is removed from result and when a negative result appears, the result is not correct.

**Workaround:**

No workaround, but avoid using this correction method to cancel  $\Delta V$  effect.

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